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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/830,635	08/02/2001	Alexander Ivanovich Taran	VALER11.001APC	1851

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EXAMINER
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NORRIS, JEREMY C

ART UNIT	PAPER NUMBER
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2827

DATE MAILED: 03/25/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	09/830,635	TARAN, ALEXANDER IVANOVIC	
	<b>Examiner</b>	<b>Art Unit</b>	
	Jeremy C. Norris	2827	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

#### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

- 1) ☒ Responsive to communication(s) filed on 12 January 2004.
- 2a) ☐ This action is **FINAL**.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

- 4) ☒ Claim(s) 24-57 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 24-36 and 46-57 is/are rejected.
- 7) ☒ Claim(s) 37-45 is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

- 9) ☒ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 27 April 2001 is/are: a) ☐ accepted or b) ☒ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All    b) ☐ Some \*    c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
  2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  3. ☒ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- \* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)  | 4) <input type="checkbox"/> Interview Summary (PTO-413)<br>Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)                                   | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)             |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)<br>Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____  |

## **DETAILED ACTION**

### ***Specification***

Applicant is reminded of the proper content of an abstract of the disclosure.

A patent abstract is a concise statement of the technical disclosure of the patent and should include that which is new in the art to which the invention pertains. If the patent is of a basic nature, the entire technical disclosure may be new in the art, and the abstract should be directed to the entire disclosure. If the patent is in the nature of an improvement in an old apparatus, process, product, or composition, the abstract should include the technical disclosure of the improvement. In certain patents, particularly those for compounds and compositions, wherein the process for making and/or the use thereof are not obvious, the abstract should set forth a process for making and/or use thereof. If the new technical disclosure involves modifications or alternatives, the abstract should mention by way of example the preferred modification or alternative.

The abstract should not refer to purported merits or speculative applications of the invention and should not compare the invention with the prior art.

Where applicable, the abstract should include the following:

- (1) if a machine or apparatus, its organization and operation;
- (2) if an article, its method of making;
- (3) if a chemical compound, its identity and use;
- (4) if a mixture, its ingredients;
- (5) if a process, the steps.

Extensive mechanical and design details of apparatus should not be given.

Applicant is reminded of the proper language and format for an abstract of the disclosure.

The abstract should be in narrative form and generally limited to a single paragraph on a separate sheet within the range of 50 to 150 words. It is important that the abstract not exceed 150 words in length since the space provided for the abstract on the computer tape used by the printer is limited. The form and legal phraseology often used in patent claims, such as "means" and "said," should be avoided. The abstract should describe the disclosure sufficiently to assist readers in deciding whether there is a need for consulting the full patent text for details.

The language should be clear and concise and should not repeat information given in the title. It should avoid using phrases which can be implied, such as, "The disclosure concerns," "The disclosure defined by this invention," "The disclosure describes," etc.

The abstract of the disclosure is objected to because of the use of the phrase "The invention relates to". Correction is required. See MPEP § 608.01(b).

### ***Drawings***

The drawings are objected to because the sectional views are not fully cross-hatched (see MPEP 608.02). A proposed drawing correction or corrected drawings are required in reply to the Office action to avoid abandonment of the application. The objection to the drawings will not be held in abeyance.

### ***Claim Rejections - 35 USC § 102***

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 24-26, 30, and 46-48 are rejected under 35 U.S.C. 102(e) as being anticipated by US 6,100,475 (hereafter Degani).

Degani discloses, referring to figure 5, a contact node comprising: at least two metallized contacts (16, 27) coupled with conductive paths arranged on surfaces of connection layers made on the base of a dielectric material and mutually aligned and interconnected electrically and mechanically by a conductive binding material (26) ,

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wherein it is made in the form of a joint between a contact made in the form of a metallized contact pad (27) coupled with the conductive paths on the surface of the connection layer, and a respective contact joined with the contact pad and made in the form of a metallized hole (15) in an upper-lying connection layer, the lower edge of the metallized hole being faced to the metallized contact pad on the surface of the underlying connection layer, and the upper edge of the hole being coupled with the conductive paths (21) on the upper surface of the upper-lying connection layer [claim 24], wherein the metallized hole is in the form of a cylinder [claim 25], wherein the upper edge of the metallized hole coupled with the conductive paths on the surface of the connection layer forms a metallized rim along the periphery of the edge [claim 26], wherein the metallized contact pad is flat [claim 30], wherein the upper and lower edges of the metallized hole have a facet [claim 46].

Similarly, Degani discloses, referring to figure 3, a contact node, comprising: a first connection layer (41) having a conductive path on a surface thereof; a second connection layer (42) deposited adjacent to the first connection layer having a conductive path on a surface thereof; and a metallized hole (43) provided through the first connection layer and having an inner surface thereof connected to the conductive path of the first connection layer; and a metallized contact pad provided on the surface of the second connection layer and connected with the conductive path of the second connection layer, wherein a conductive binding material (45) is deposited in the metallized hole to be in contact with the inner surface of the metallized hole and the metallized contact pad so as to form connection between the first and second

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connection layers [claim 47], wherein the metallized hole is in a form of a cylinder [claim 48].

Claims 24, 27-31, 34, 35, 46, 47, 49, 53, and 54 are rejected under 35 U.S.C. 102(e) as being anticipated by US 6,087,597 (hereafter Shimada).

Shimada discloses, referring to figure 2, a contact node comprising: at least two metallized contacts coupled with conductive paths arranged on surfaces of connection layers made on the base of a dielectric material and mutually aligned and interconnected electrically and mechanically by a conductive binding material (13), wherein it is made in the form of a joint between a contact made in the form of a metallized contact pad (31) coupled with the conductive paths on the surface of the connection layer, and a respective contact joined with the contact pad and made in the form of a metallized hole (23) in an upper-lying connection layer, the lower edge of the metallized hole being faced to the metallized contact pad on the surface of the underlying connection layer, and the upper edge of the hole being coupled with the conductive paths (24) on the upper surface of the upper-lying connection layer [claim 24], wherein the metallized hole is made in the form of a truncated cone, the lower base of the truncated cones being faced to the contact pad on the surface of the underlying connection layer, and the upper base of the truncated cones being coupled with the conductive paths on the upper surface of the upper-lying connection layer [claim 27], wherein the upper edge of the metallized hole coupled with the conductive paths on the surface of the connection layer forms a metallized rim long the periphery of the edge [claim 28], wherein an integrated circuit chip (41) oriented by its metallized contact pads

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to the corresponding metallized holes in the upper-lying connection layer is used as a connection layer with the metallized contact pads respective to the metallized holes in the upper-lying connection layer [claim 29], wherein the metallized contact pad is flat [claim 30], further comprising a protrusion (31) interacting with the respective metallized hole formed in the center of the metallized contact pad respective to the metallized hole [claim 31], wherein the protrusion is in the form of a sphere (see col. 2, lines 20-30) [claim 34], wherein the protrusion is made of a conductive material (see col. 3, lines 30-35) [claim 35], wherein the upper and lower edges of the metallized hole have a facet [claim 46].

Similarly, Shimada discloses, referring to figure 2, a contact node, comprising: a first connection layer (21) having a conductive path on a surface thereof; a second connection layer (30) deposited adjacent to the first connection layer having a conductive path on a surface thereof; and a metallized hole (23) provided through the first connection layer and having an inner surface thereof connected to the conductive path of the first connection layer; and a metallized contact pad (31) provided on the surface of the second connection layer and connected with the conductive path of the second connection layer, wherein a conductive binding material (13) is deposited in the metallized hole to be in contact with the inner surface of the metallized hole and the metallized contact pad so as to form connection between the first and second connection layers [claim 47], wherein the metallized contact pad has a metallized protrusion (11) in a form of a sphere (see col. 2, lines 20-30) in the conductive binding

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obvious, to one having ordinary skill in the art, at the time of invention, to use any of the rod, cylinder, or cone shapes as the shape for the protrusion in the invention of Shimada. The motivation for doing so would have been to utilize the shape that most facilitates insertion into the corresponding through hole (see Shimada, col. 7, lines 15-20).

Claim 36 is rejected under 35 U.S.C. 103(a) as being unpatentable over Shimada in view of US 5,729,440 (hereafter Jimarez).

Shimada discloses the claimed invention as described above except Shimada does not specifically state that the protrusion is made of a solder. However, Shimada teaches that the protrusion may be formed from any metal as long as the melting point of the metal is higher than the melting point of the joining solder (stated to be ~ 180° C). There are many high-temperature solders having melting points higher than this amount known in the art as evidenced by Jiminez (see col. 3, lines 5-15). Therefore, it would have been obvious, to one having ordinary skill in the art, at the time of invention, to use a high temperature solder that is known in the art, as evidenced by Jiminez, as the material for the core in the invention of Shimada. The motivation for doing so would have been to use a known material having suitable solidity at the liquidous temperature of the joining solder.



***Allowable Subject Matter***

Claims 37-45 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The following is a statement of reasons for the indication of allowable subject matter:

Claim 37 states the limitation "further comprising a contact made in the form of a rod fixed in the underlying connection layer orthogonally to its surface inserted into the metallized hole". This limitation, in conjunction with the other claimed limitations was neither found to be disclosed in, nor suggested by the prior art. Claim 44 states the limitation "wherein the diameter D of the upper base of the truncated cone, the width h of the metallized rim, the diameter d of the lower base of the truncated cone, the thickness t of the dielectric material of the connection layer and the minimal width L of the respective metallized contact pad on the underlying connection layer are coupled with the following relationship:  $L \geq D + 2h = d + 2t + 2h$ ". This limitation, in conjunction with the other claimed limitations was neither found to be disclosed in, nor suggested by the prior art.

***Conclusion***

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

US 5,920,123      Moden,


US 6,010,769	Sasaoka et al.,
US 6,013,877	Degani et al.,
US 6,054,761	McCormack et al..

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jeremy C. Norris whose telephone number is 571-272-1932. The examiner can normally be reached on Monday - Friday, 9:30 am - 5:30 pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kamand Cuneo can be reached on 571-272-1957. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

JCSN

  
**KAMAND CUNEO**  
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**TECHNOLOGY CENTER 2800**